

TSMC-01-1063

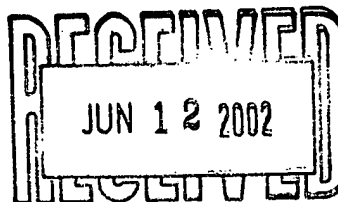


May 1, 2002

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To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603



Subject:

Serial No. 10/058,473-01/28/02

Ken Chen et al.

ENHANCED ADHESION STRENGTH BETWEEN
MOLD RESIN AND POLYIMIDE

Grp. Art Unit: 2812

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.


The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner of Patents and
Trademarks, Washington, D.C. 20231, on May 2, 2002.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

 5/2/02

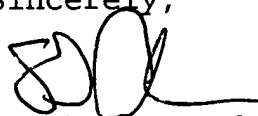
U.S. Patent 5,937,279 to Sawada et al., "Semiconductor Device, and Manufacturing Method of the Same," discloses a packaging process to reduce cracks due to stress.

U.S. Patent 5,883,001 to Jin et al., "Integrated Circuit Passivation Process and Structure," discloses a process to improve Cu pad adhesion.

U.S. Patent 5,940,277 to Farnworth et al., "Semiconductor Device Including Combed Bond Pad Opening, Assemblies and Methods," discusses a semiconductor device including bond pads disposed proximate an edge thereof, and an overcoat layer.

U.S. Patent 6,191,023 to Chen, "Method of Improving Copper Pad Adhesion," relates to a new improved method and structure in the fabricating of aluminum metal pads.

Sincerely,

A handwritten signature in black ink, appearing to be 'SBA', written over a horizontal line.

Stephen B. Ackerman,
Reg. No. 37761